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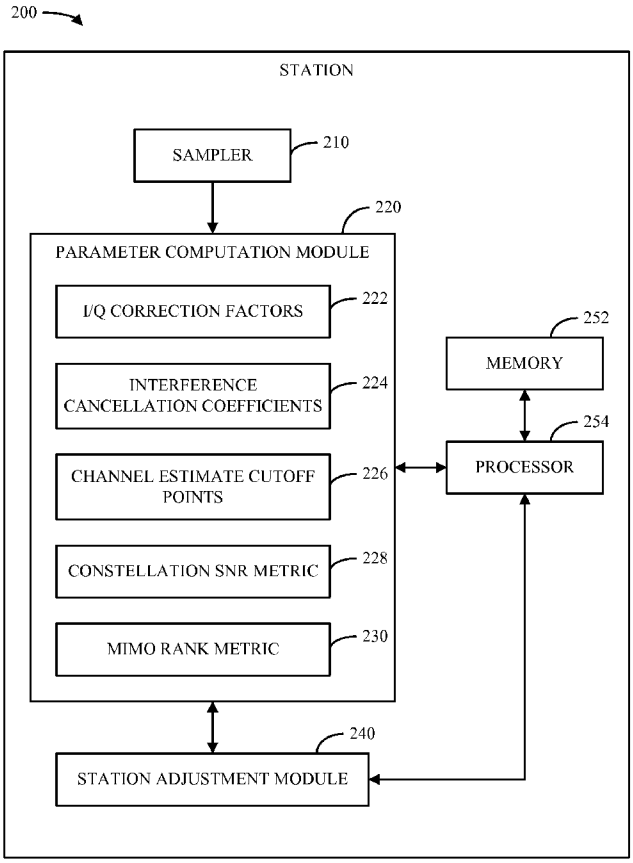

(57) Abstract: A stencil printer apparatus for depositing a solder paste onto the surface of the electronic substrate, comprising a frame, a stencil coupled to the frame, the stencil having a plurality of apertures, a dispenser coupled to the frame, the stencil and the dispenser being configured to deposit the solder paste onto the electronic substrate, an imaging system (121) constructed and arranged to capture an image of the electronic substrate, and a controller coupled to the imaging- system and configured to control movement of the imaging system to capture the image. The imaging system (121) comprises a camera element (201, 203) configured to capture the image of at least the portion of the surface of the electronic substrate (111), and a first illumination element (209) comprising a long-wavelength light source configured to illuminate at least the portion of the surface of the electronic substrate by generating long-wavelength light. Other embodiments and methods are disclosed.

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NO, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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